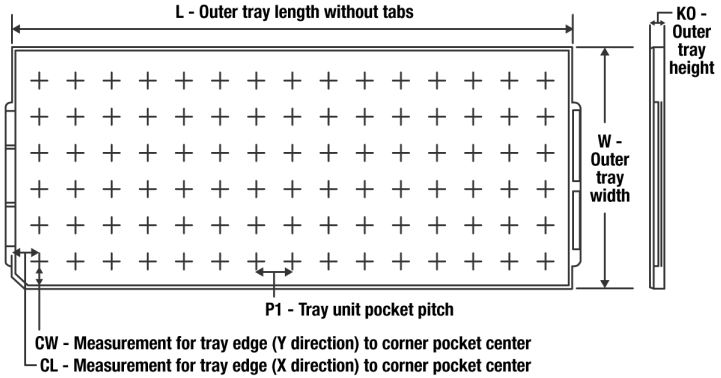
Carrier Material Report for TMS32C6713BGDPA200

Tray Information:



Device	Package Drawing	Package Type	Pins	SPQ	Unit Array Matrix	Max Temp (°C)	L (mm)	W (mm)	K0 (µm)	P1 (mm)	CL (mm)	CW (mm)
TMS32C6713BGDPA200	GDP	BGA	272	40	4x10	150	315	135.9	7620	29.2	26.1	24.15

Images above are just a representation of the carrier. Actual carrier may vary. Please reference the dimensions provided in the table.

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